INTEGRATED CIRCUITS

DATA SHEET



74ALVCH16823

18-bit bus-interface D-type flip-flop with reset and enable (3-State)

Product specification

1998 Jul 29

IC24 Data Handbook





18-bit D-type flip-flop (3-State)

74ALVCH16823

FEATURES

- Wide supply voltage range of 1.2V to 3.6V
- Complies with JEDEC standard no. 8-1A.
- CMOS low power consumption
- Direct interface with TTL levels
- Current drive ± 24 mA at 3.0 V
- Multibyte[™]flow-through standard pin-out architecture
- Low inductance multiple V_{CC} and GND pins to minimize noise and ground bounce
- All data inputs have bus hold
- Output drive capability 50Ω transmission lines @ 85°C

DESCRIPTION

The 74ALVCH16823 is a 18-bit edge-triggered flip-flop featuring separate D-type inputs for each flip-flop and 3-state outputs for bus oriented applications. Incorporates bushold data inputs which eliminate the need for external pull-up resistors to hold unused inputs. The74ALVCH16823 consists of two sections of nine edge-triggered flip-flops. A clock (CP) input, an output-enable (OE) input, a Master reset (MR) input and a clock-enable(CE) input are provided for each total 9-bit section.

With the clock-enable (CE) input LOW, the D-type flip-flops will store the state of their individual D-inputs that meet the set-up and hold time requirements on the LOW-to-HIGH CP transition. Taking CE HIGH disables the clock buffer, thus latching the outputs. Taking the Master reset (MR) input LOW causes all the Q outputs to go LOW independently of the clock.

When $\overline{\text{OE}}$ is LOW, the contents of the flip-flops are available at the outputs. When the $\overline{\text{OE}}$ is HIGH, the outputs go to the high impedance OFF-state. Operation of the OE input does not affect the state of flip-flops.

Active bus hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

QUICK REFERENCE DATA

GND = 0V; $T_{amb} = 25^{\circ}C$; $t_r = t_f \le 2.5$ ns

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT	
t _{PHL} /t _{PLH}	Propagation delay CP to Qn	2.1 2.1	ns		
F _{max}	Maximum clock frequency	V _{CC} = 2.5V, CL = 30pF V _{CC} = 3.3V, CL = 50pF	300 350	MHz	
C _I	Input capacitance	capacitance			
C _{PD}	Power dissipation capacitance per latch	V _I = GND to V _{CC} ¹ Outputs enabled	16	pF	
CPD	Fower dissipation capacitance per laten	Outputs disabled	10	PΓ	

NOTES:

 $P_D = C_{PD} \times V_{CC}^2 \times f_i + \Sigma (C_L \times V_{CC}^2 \times f_0)$ where: $f_i = \text{input frequency in MHz}$; $C_L = \text{output load capacity in pF}$; $f_0 = \text{output frequency in MHz}$; $V_{CC} = \text{supply voltage in V}$;

 $\Sigma (C_L \times V_{CC}^2 \times f_0) = \text{sum of outputs.}$

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
56-Pin Plastic SSOP Type II	-40°C to +85°C	74ALVCH16823 DL	ACH16823 DL	SOT371-1
56-Pin Plastic TSSOP Type II	-40°C to +85°C	74ALVCH16823 DGG	ACH16823 DGG	SOT364-1

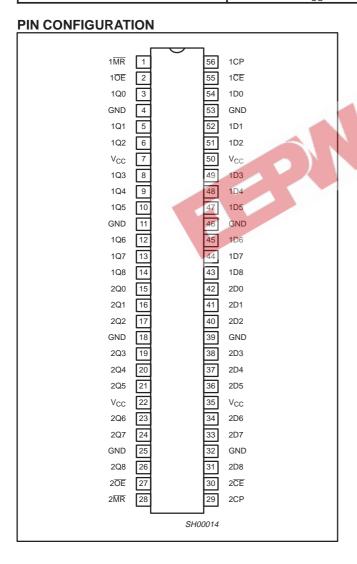
 C_{PD} is used to determine the dynamic power dissipation (P_D in μW):

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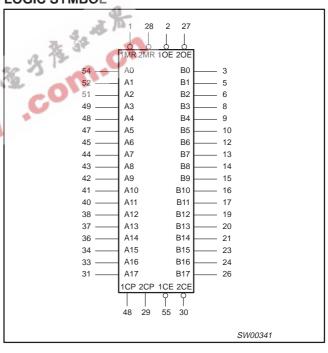
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PIN DESCRIPTION

PIN NUMBER	SYMBOL	FUNCTION
2, 27	10E, 20E	Output enable input (active-Low)
54, 52, 51, 49, 48, 47, 45, 44, 43 42, 41, 40, 38, 37, 36, 34, 33, 31	1D0-1D8 2D0-2D8	Data inputs
3, 5, 6, 8, 9, 10, 12, 13, 14 15, 16, 17, 19, 20, 21, 23, 24, 26	1Q0-1Q8 2Q0-2Q8	Data outputs
56, 29	1CP, 2CP	Clock pulse input (active rising edge)
55, 30	1CE, 2CE	Clock enable input (active-Low)
1, 28	1MR, 2MR	Master reset input (active-Low)
4, 11, 18, 25, 32, 39, 46, 53	GND	Ground (0V)
7, 22, 35, 50	V _{CC}	Positive supply voltage



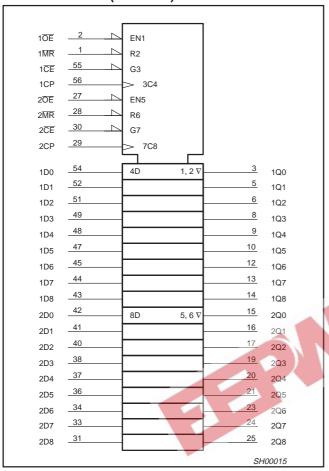
LOGIC SYMBOL



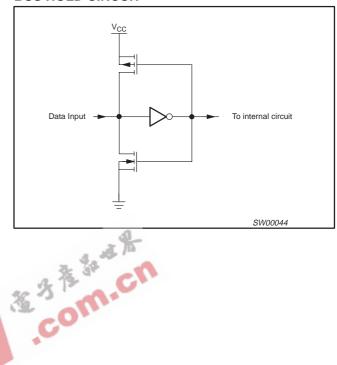
18-bit D-type flip-flop (3-State)

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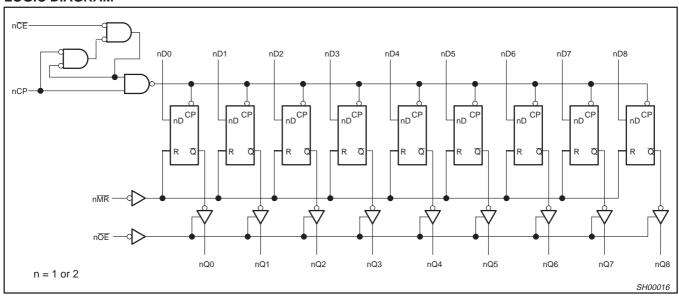
LOGIC SYMBOL (IEEE/IEC)



BUS HOLD CIRCUIT



LOGIC DIAGRAM



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FUNCTION TABLE

		INPUTS			OUTPUT	OPERATING MODES
nŌĒ	nMR	nCE	nCP	nDx	nQx	OPERATING MODES
L	L	Х	Х	Х	L	Clear
L	Н	L	↑	h	Н	Load and read data
L	Н	L	1	Ţ	L	Load and read data
L	Н	L	L	Х	Q_0	Hold
L	Н	Н	Х	Х	Q_0	noiu
Н	Х	Х	Х	Х	Z	Disable outputs

H = HIGH voltage level

= HIGH voltage level one set-up time prior to the Low-to-High clock transition

= LOW voltage level

= LOW voltage level one set-up time prior to the Low-to-High clock transition

Χ = Don't care

RECOMMENDED OPERATING CONDITIONS

↑ = LOW to	ENDED OPERATING CONDITIONS	4.4	38-		
SYMBOL	PARAMETER	CONDITIONS	LIN	IITS	UNIT
STWIBOL	PARAIVIETER	CONDITIONS	MIN	MAX] UNIT
V	DC supply voltage 2.5V range (for max. speed performance @ 30 pF output load)		2.3	2.7	
V _{CC}	DC supply voltage 3.3V range (for max. speed performance @ 50 pF output load)		3.0	3.6	
V _{CC}	DC supply voltage (for low-voltage applications)		1.2	3.6	V
	DC lanut voltage renge	for data input pins	0	V _{CC}	V
V _I	DC Input voltage range	for control pins	0	5.5	V
Vo	DC output voltage range		0	V _{CC}	V
T _{amb}	Operating free-air temperature range		-40	+85	°C
t _r , t _f	Input rise and fall times	V _{CC} = 2.3 to 3.0V V _{CC} = 3.0 to 3.6V	0 0	20 10	ns/V

ABSOLUTE MAXIMUM RATINGS

In accordance with the Absolute Maximum Rating System (IEC 134). Voltages are referenced to GND (ground = 0V).

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +4.6	V
I _{IK}	DC input diode current	V ₁ < 0	- 50	mA
\/	DC input voltage	For control pins ¹	-0.5 to +5.5	V
VI	DC input voltage	For data inputs ¹	-0.5 to V _{CC} +0.5	1 '
I _{OK}	DC output diode current	$V_O > V_{CC}$ or $V_O < 0$	±50	mA
Vo	DC output voltage	Note 1	-0.5 to V _{CC} +0.5	٧
I _O	DC output source or sink current	$V_{O} = 0$ to V_{CC}	±50	mA
I _{GND} , I _{CC}	DC V _{CC} or GND current		±100	mA
T _{stg}	Storage temperature range		-65 to +150	°C
P _{TOT}	Power dissipation per package –plastic medium-shrink (SSOP) –plastic thin-medium-shrink (TSSOP)	For temperature range: –40 to +125 °C above +55°C derate linearly with 11.3 mW/K above +55°C derate linearly with 8 mW/K	850 600	mW

^{1.} The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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DC ELECTRICAL CHARACTERISTICS

Over recommended operating conditions. Voltage are referenced to GND (ground = 0 V).

]		
Vol I	$ \text{HIGH level Input voltage } \\ HIGH level Input voltage \\ \begin{array}{c ccccccccccccccccccccccccccccccccccc$							
			MIN	TYP ¹	MAX	1		
		V _{CC} = 1.2V	Vcc					
W	HICH lovel Input voltage	V _{CC} = 1.8V	0.7*V _{CC}	0.9		1 ,		
VIΗ	High level input voltage	V _{CC} = 2.3 to 2.7V	1.7	1.2		1 °		
		V _{CC} = 2.7 to 3.6V	2.0	1.5		1		
		$V_{CC} = 1.2V$		-	GND			
\/	LOW lovel Input veltage	$V_{CC} = 1.8V$		0.9	0.2*V _{CC}	1 ,		
۷IL	LOW level input voltage	V _{CC} = 2.3 to 2.7V		1.2	0.7	1		
		V _{CC} = 2.7 to 3.6V		1.5	0.8	1		
		$V_{CC} = 1.8 \text{ to } 3.6 \text{V}; V_I = V_{IH} \text{ or } V_{IL}; I_O = -100 \mu\text{A}$	V _{CC} -0.2	Vcc	-			
		$V_{CC} = 1.8V; V_I = V_{IH} \text{ or } V_{IL}; I_O = -6\text{mA}$	V _{CC} -0.4	V _{CC} -0.10	-	1		
		$V_{CC} = 2.3V; V_I = V_{IH} \text{ or } V_{IL}; I_O = -6\text{mA}$	V _{CC} _0.3	V _{CC} _0.08	-	1		
V_{OH}	HIGH level output voltage	$V_{CC} = 2.3V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = -12$ mA	V _{CC} -0.5	V _{CC} -0.17	-	1 ∨		
		$V_{CC} = 2.3V; V_I = V_{IH} \text{ or } V_{IL}; I_O = -18\text{mA}$	V _{CC} -0.6	V _{CC} -0.26	-	1		
		$V_{CC} = 2.7V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = -12$ mA	V _{CC} _ 0.5	V _{CC} _0.14	-	1		
		$V_{CC} = 3.0V$; $V_{I} = V_{IH}$ or V_{IL} ; $I_{O} = -24$ mA	V _{CC} – 1.0	V _{CC} -0.28	-	1		
		$V_{CC} = 1.8 \text{ to } 3.6 \text{V}; \ V_{I} = V_{IH} \text{ or } V_{IL}; \ I_{O} = 100 \mu \text{A}$		GND	0.20			
		$V_{CC} = 1.8V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = 6mA$		0.09	0.30	1		
		$V_{CC} = 2.3V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 6\text{mA}$		0.07	0.20	1		
V_{OI}	LOW level output voltage	$V_{CC} = 2.3V; V_{I} = V_{IH} \text{ or } V_{IL}; I_{O} = 12\text{mA}$		0.15	0.40	1 v		
OL		$V_{CC} = 2.3V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 18\text{mA}$		0.23	0.60	1		
		$V_{CC} = 2.7V$; $V_{I} = V_{IH}$ or V_{IL} ; $I_{O} = 12mA$	-	0.14	0.40	1		
		$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 24\text{mA}$		0.27	0.55	1		
	Input leakage current per	V _{CC} = 1.8 to 3.6V;	-	0.4		_		
ı.	control pin	V _I = 5.5V or GND		0.1	5	μΑ		
·η	Input leakage current per data	$V_{CC} = 1.8 \text{ to } 3.6 \text{V};$		0.1	5	1 μΛ		
	pin	$V_I = V_{CC}$ or GND				┞		
	Input current for common I/O	V _{CC} = 1.8 to 2.7V; V _I = V _{CC} or GND		0.1	10			
I_{IHZ}/I_{ILZ}	pins	V _{CC} = 3.6V;		0.4	4.5	μA		
		V _I = V _{CC} or GND		0.1	15			
		$V_{CC} = 1.8 \text{ to } 2.7 \text{V}; V_I = V_{IH} \text{ or } V_{IL};$		0.1	5			
107	3-State output OFF-state	$V_O = V_{CC}$ or GND		···	, i	μΑ		
02	current	$V_{CC} = 2.7 \text{ to } 3.6 \text{V}; V_{I} = V_{IH} \text{ or } V_{IL}; V_{O} = V_{CC} \text{ or GND}$		0.1	10	`		
	Additional quiescent supply					 		
ΔI_{CC}	current given per data I/O pin	$V_{CC} = 2.7V \text{ to } 3.6V; V_I = V_{CC} - 0.6V; I_O = 0$		150	750	μΑ		
	Bus hold LOW sustaining	$V_{CC} = 2.3V; V_1 = 0.7V^2$	45	-		1		
^I BHL	current	$V_{CC} = 3.0V; V_1 = 0.8V^2$	75	150		μA		
	Bus hold HIGH sustaining	$V_{CC} = 2.3V; V_I = 1.7V^2$	-45			1		
Iвнн	current	$V_{CC} = 3.0V; V_I = 2.0V^2$	-75	-175		μΑ		
,	Don't halfil OW and the	$V_{CC} = 2.7V^2$	300			١.		
IBHLO	Bus hold LOW overdrive current	$V_{CC} = 3.6V^2$	450			μA		
	Bus hold HIGH overdrive	$V_{CC} = 2.7V^2$	-300			١.		
Івнно	current	$V_{CC} = 3.6V^2$	-450			μA		

NOTES:

All typical values are at T_{amb} = 25°C.
 Valid for data inputs of bus hold parts.

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AC CHARACTERISTICS FOR V_{CC} = 2.3V TO 2.7V RANGE AND $V_{CC} < 2.3 \text{V}$

 $GND = 0V; \ t_r = t_f \leq 2.0ns; \ C_L = 30pF$

						LIM	TS			
SYMBOL	PARAMETER	WAVEFORM	Vcc	= 2.3 to	2.7V	V	_{CC} = 1.8	3V	V _{CC} = 1.2V	UNIT
			MIN	TYP ^{1, 2}	MAX	MIN	TYP1	MAX	TYP ¹	ns ns ns ns ns ns ns
t _{PLH} /t _{PHL}	Propagation delay nCP to nQ _n	1, 5	1.0	2.8	4.9	1.5	4.5	7.5	10.6	ns
t _{PLH} /t _{PHL}	Propagation delay nMR to nQ _n	2, 5	1.0	2.9	5.0	1.5	4.6	7.4	9.9	ns
t _{PZH} /t _{PZL}	3-State output enable time $n\overline{\text{OE}}_n$ to nQ_n	4, 5	1.0	2.8	5.3	1.5	4.4	7.7	10.4	ns
t _{PHZ} /t _{PLZ}	3-State output disable time $n\overline{\text{OE}}_n$ to nQ_n	4, 5	1.0	2.2	4.1	1.5	3.3	5.5	6.7	ns
t	nCP pulse width	1, 5	3.0	1.6		4.0	2.0			ne
t _W	nMR pulse width, LOW	3, 5	3.0	0.4		4.0	0.8			113
tau	Set up time nD _n to nCP	3, 5	1.2	0.2		1.5	0.2			ne
t _{SU}	Set up time nCE to nCP	3, 3	1.8	-0.2	J	2.0	-0.2			115
	Hold time nD _n to nCP	3, 5	0.8	-0.1	4.	0.6	-0.2			no
t _h	Hold time nCE to nCP	3, 5	0.3	0.2	a.	0.3	0.2			115
t _{rec}	Recovery time nMR to nCP	2, 5	1.0	0.3	1	0.8	0.2			ns
F _{max}	Maximum clock pulse frequency	1, 5	150	300	84.	125	250		Ì	MHz

NOTE:

- All typical values are measured at T_{amb} = 25°C.
 Typical value is measured at V_{CC} = 2.5V.

AC CHARACTERISTICS FOR $V_{CC} = 3.0 \text{V}$ TO 3.6V RANGE AND $V_{CC} = 2.7 \text{V}$

GND = 0V; $t_r = t_f \le 2.5 \text{ns}$; $C_L = 50 \text{pF}$

					LII	MITS			
SYMBOL	PARAMETER	WAVEFORM	Vc	_C = 3.0 ± 0	0.3V	'	V _{CC} = 2.7	V	UNIT
			MIN TYP ^{1, 2}		MAX	MIN	TYP ¹	MAX	
t _{PLH} /t _{PHL}	Propagation delay nCP to nQ _n	1, 5	1.0	2.5	3.7	1.0	2.7	4.3	ns
t _{PLH} /t _{PHL}	Propagation delay nMR to nQ _n	2, 5	1.0	2.6	4.0	1.0	3.1	4.6	ns
t_{PZH}/t_{PZL}	3-State output enable time nOE _n to nQ _n	4, 5	1.0	2.5	4.3	1.0	3.1	5.2	ns
t _{PHZ} /t _{PLZ}	3-State output disable time nOE _n to nQ _n	4, 5	1.0	2.8	3.9	1.0	3.1	4.3	ns
t _W	nCP pulse width HIGH or LOW	1, 5	2.5	1.4		3.0	1.6		ns
τW	nMR pulse width HIGH or LOW	3, 5	2.5	0.3		3.0	0.6		113
tou	Set up time nD _n to nCP	3, 5	1.2	0.2		1.5	0.4		ns
t_{SU}	Set up time nCE to nCP	3, 3	1.5	-0.1		1.9	-0.1		1115
t .	Hold time nD _n to nCP	3, 5	0.8	0.0		0.6	-0.2		ns
t _h	Hold time nCE to nCP	3, 5	0.5	0.1		0.4	0.1		1115
t _{rec}	Recovery time nMR to nCP	2, 5	1.0	0.2		0.8	0.1		ns
F _{max}	Maximum clock pulse frequency	1, 5	200	350		150	300		MHz

- 1. All typical values are measured at $T_{amb} = 25$ °C.
- 2. Typical value is measured at $V_{CC} = 3.3V$.

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AC WAVEFORMS FOR V_{CC} = 2.3V TO 2.7V AND V_{CC} < 2.3V RANGE

 $V_M = 0.5 V_{CC}$ $V_X = V_{OL} + 0.15V$ $V_Y = V_{OH} - 0.15V$

Vol. and VoH are the typical output voltage drop that occur with the output load.

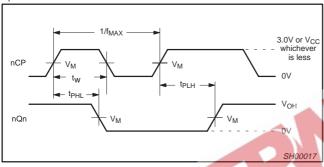
 $V_I = V_{CC}$

AC WAVEFORMS FOR $V_{CC} = 3.0V$ TO 3.6V AND $V_{CC} = 2.7V RANGE$

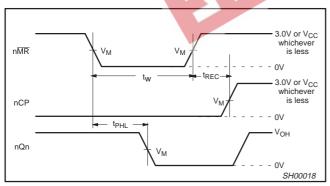
 $V_{M} = 1.5 V$ $V_{X} = V_{OL} + 0.3 V$

 $V_{Y} = V_{OH} - 0.3V$

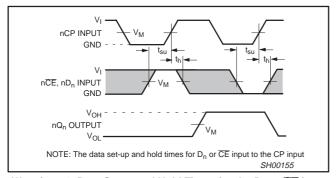
V_{OL} and V_{OH} are the typical output voltage drop that occur with the output load.



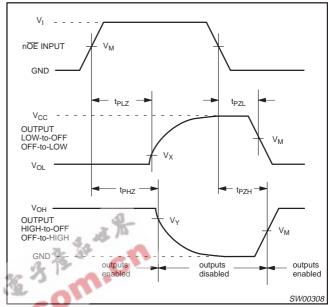
Waveform 1. Clock (nCP) to Output (nQn) Propagation Delays, Clock Pulse Width, and Maximum Clock Pulse Frequency



Waveform 2. Master Reset (MR) Pulse Width, MR to Output propagation Delay and MR to Clock Recovery Time

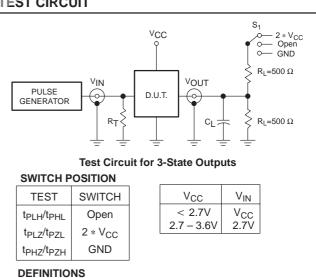


Waveform 3. Data Setup and Hold Times for the D_n or $\overline{\text{CE}}$ input to the CP input



Waveform 4. 3-State Enable and Disable Times

TEST CIRCUIT



R_L = Load resistor

 C_L = Load capacitance includes jig and probe capacitance

 R_T = Termination resistance should be equal to Z_{OUT} of pulse generators.

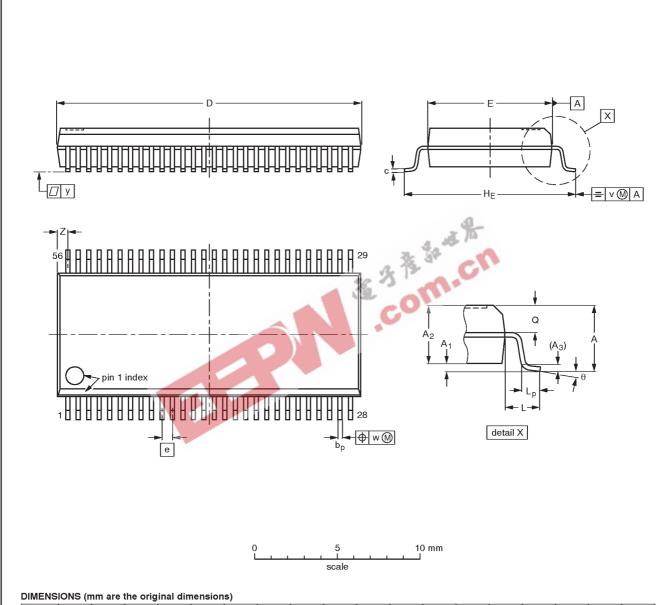
Waveform 5. Load circuitry for switching times

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SSOP56: plastic shrink small outline package; 56 leads; body width 7.5 mm

SOT371-1



	(-,												
UNIT	A max.	Α1	A ₂	A ₃	bp	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	2.8	0.4 0.2	2.35 2.20	0.25	0.3 0.2	0.22 0.13	18.55 18.30	7.6 7.4	0.635	10.4 10.1	1.4	1.0 0.6	1.2 1.0	0.25	0.18	0.1	0.85 0.40	8° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

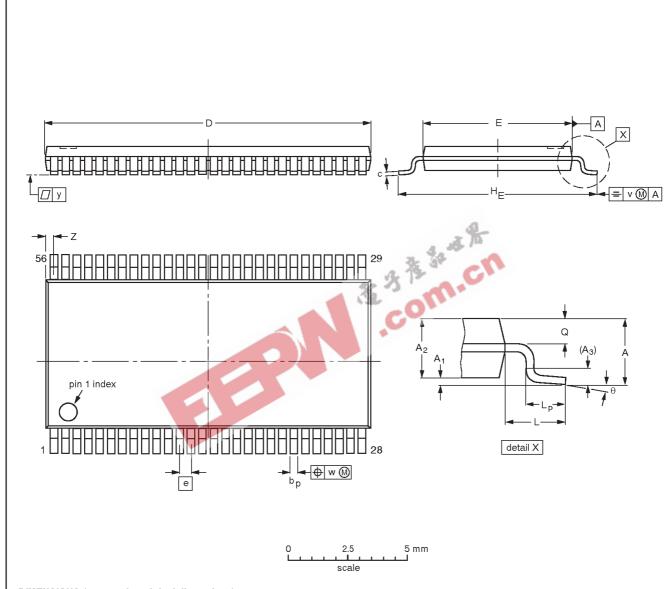
OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT371-1		MO-118AB			93-11-02 95-02-04

18-bit bus-interface D-type flip-flop with reset and enable (3-State)

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TSSOP56: plastic thin shrink small outline package; 56 leads; body width 6.1mm

SOT364-1



DIMENSIONS (mm are the original dimensions).

UNIT	A max.	A ₁	A ₂	А3	bp	c	D ⁽¹⁾	E ⁽²⁾	e	HE	L	Lp	Q	>	w	у	Z	θ
mm	1.2	0.15 0.05	1.05 0.85	0.25	0.28 0.17	0.2 0.1	14.1 13.9	6.2 6.0	0.5	8.3 7.9	1.0	0.8 0.4	0.50 0.35	0.25	0.08	0.1	0.5 0.1	8° 0°

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN	ISSUE DATE
	IEC	JEDEC	EIAJ		PROJECTION	1990E DATE
SOT364-1		MO-153EE				-93-02-03- 95-02-10

18-bit bus-interface D-type flip-flop with reset and enable (3-State)

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NOTES



18-bit bus-interface D-type flip-flop with reset and enable (3-State)

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Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

^[1] Please consult the most recently issued datasheet before initiating or completing a design.

Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

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